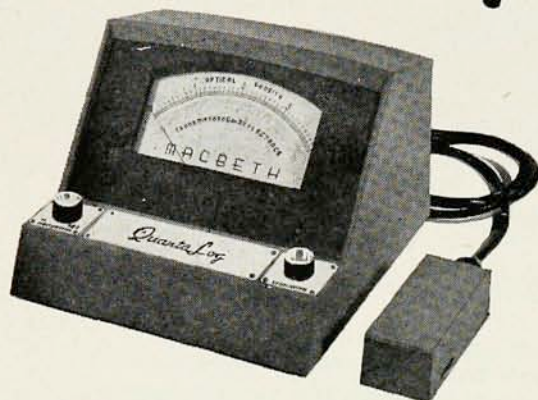


**IT'S HERE!
A LOW COST, HIGH QUALITY
DENSITOMETER**

THE NEW
MACBETH

QuantaLog



**A Universal Instrument for Densitometry,
Photometry and Light Measurement.**

**A quality Instrument for Under
\$400.00** (NOT INCLUDING
ATTACHMENTS).

Features:

1. Direct reading, in black-and-white or color, through narrow band pass filters, to density 4.0.
2. Large easy to read scale 0-4.0 density units, eliminates scale changing and tracking error. Scale is linear with density. Instrument has an accuracy of ± 0.02 density units over entire scale.
3. Electronic compensating circuit allows for the calibration of several instruments to the same density standard.
4. Low power consumption (25 watts), electronic stability 95-120V input from ordinary wall plug over a miniaturized sensitive dynode feedback circuit.

New building block design of the Macbeth QuantaLog allows for fast simple connection to such optical components as: a reflection head, transmission (color and black-and-white) and digital readout attachments, as well as many others which are not yet off the drawing boards. You can see the new Macbeth QuantaLog, "The Instrument that will never go out of Date" at:

Photo-Lithographers Show
Hotel Statler
Boston 10, Massachusetts
September 10, 11, 12 and 13

American Photoengravers
Convention
Netherland Hilton Hotel
Cincinnati, Ohio
October 13, 14 and 15

SMPTE Show
Sheraton-Cadillac Hotel
Detroit, Mich.

Oct. 20-24
Booth No. 22

If you would like to receive complete literature and specifications on the new Macbeth QuantaLog, please address correspondence to Dept. P.T., Macbeth Instrument Corporation, P.O. Box 950, Newburgh, New York.

MACBETH

INSTRUMENT CORPORATION

P.O. Box 950

Newburgh, New York

the more than 25 sponsoring societies will present technical papers on the latest developments in the field of atomic energy applications for peaceful purposes. 500-word summaries of proposed papers may be submitted to the secretary of any of the sponsoring societies before October 1. A list of the sponsoring organizations and further information on the conference are available from the Engineers Joint Council, 29 West 39th Street, New York 18, N. Y.

The Atomic Energy Management Conference, sponsored by the Atomic Industrial Forum and the National Industrial Conference Board, will present nuclear development information to management. Information may be obtained from Charles Robbins, 3 East 54th Street, New York 22, N. Y.

The Hot Laboratories and Equipment Conference will be sponsored and conducted by the Hot Laboratory Committee and will deal with the technical details of the development of equipment and operation of laboratories. For information contact Frank Ring, Jr., Oak Ridge National Laboratory, Oak Ridge, Tenn.

Atomfair, an exhibition sponsored by the Atomic Industrial Forum, will feature the latest developments in industrial uses of atomic energy. For further information contact either the director, Joseph V. Friel, or the exhibits manager, Harold F. Grebe, 304 Architects Building, Philadelphia 3, Pa.

Mechanical Properties of Intermetallic Compounds

FUNDAMENTAL behaviors, phenomenology, and experimental techniques of all intermediate phases in binary or higher order systems of true metals, including superlattices, are on the proposed agenda of a symposium on Mechanical Properties of Intermetallic Compounds to be held during the Electrochemical Society meeting scheduled for May 3-7 in Philadelphia, Pa. Titles of proposed papers should be sent immediately and 75-word abstracts (in triplicate) must be sent by January 1 to Dr. J. H. Westbrook, General Electric Research Laboratory, P. O. Box 1088, Schenectady, N. Y.

Electronic Components

NEW Concepts for the Space Age will be the theme of the 1959 Electronic Components Conference scheduled for May 6-8 at the Benjamin Franklin Hotel in Philadelphia. The program will include papers on components and their application in space vehicles, microminiaturization, developments in materials and their application to components, radiation effects, reliability and failure, new electronic techniques, semiconductors and electron tube devices, instrumentation and control devices, and other related topics. Abstracts (200 words) should be sent before October 1 to the technical program chairman, Brig. Gen. Edwin R. Petzing, AGEPS Secretariat, University of Pennsylvania, 200 S. 33rd St., Philadelphia 4, Pa.